REMARKS

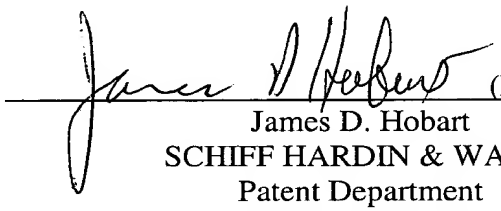
Claims 1-3, 8 and 10-25 are presented for examination.

By this amendment, claims 1 and 21 have been further amended to distinguish the claims over the prior art. It is noted that in the Advisory Action, the Examiner contends that, "The applicant has argued that the references do not teach the aluminizing as a way to cause the powders of the slip layer to be diffused together. This is not persuasive as the applicant is arguing limitations not present in the claims. The applicant's arguments are not commensurate in the scope of the claims." By this amendment, claim 1 has been amended to state alitizing to cause diffusion joining and compacting of the slip layer, and claim 21 has been amended to state that the heat treatment causes a union of the layer with the component part and alitizing to strengthen the union by diffusion and to compact the layer to form an adhesion layer. These changes are all shown in the marked-up version attached as an Appendix, with insertions being underlined and deletions being in brackets.

It is submitted that these features are not taught or suggested by the references of record. For example, Olson et al, while teaching aluminizing, does not teach or suggest that this would cause diffusion joining and compacting of the slip layer and it is submitted that Rigney, while teaching applying a slurry, is completely silent about aluminizing. Thus, it is submitted that there is no clear teaching in either of the references of obtaining the method recited in claim 1, as now amended, wherein the alitizing causes diffusion joining and compacting of the slip layer, and the method recited in claim 21, as now amended, wherein the alitizing strengthens the union by diffusion and to compact the layer to form the adhesion layer. Thus, it is submitted that the two independent claims, 1 and 21, are allowable over the references of record. It is also submitted that dependent claims 2, 3, 8, 10-20 and 22-25 are allowable for the reasons that parent claim 1 is allowable.

In view of the amendments and explanations contained hereinabove, it is respectfully submitted that this application is now in condition for immediate formal allowance and further reconsideration to that end is earnestly solicited.

Respectfully submitted,



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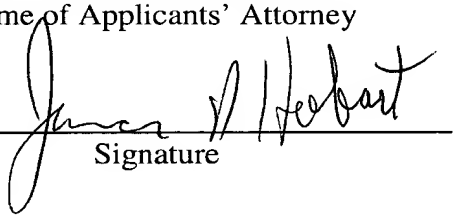
DATED: October 16, 2002

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on October 16, 2002.

James D. Hobart
Name of Applicants' Attorney



Signature

October 16, 2002
Date

APPENDIX

Version with markings to show changes made.

IN THE CLAIMS:

--1. (Amended) Method for manufacturing an adhesion layer for a heat insulating layer that is applied onto a component part, the method comprising the steps:

a) producing a slip by mixing powders containing at least one of the elements Cr, Ni or CE with a binding agent;

b) applying the slip onto the component part;

c) drying the slip at temperatures from room temperature through 300°C;

d) alitizing to cause diffusion joining and compacting of the slip layer to form the adhesion layer, whereby the method is controlled so that the adhesion layer comprises a structure having a grain size less than 75µm and a cavity proportion from 0 through 40%; and

e) applying a heat insulating layer on the adhesive layer.--

--21. (Amended) A method for manufacturing an adhesion layer for a heat insulating layer that is applied onto a component part, the method comprising the steps of:

a) producing a slip by mixing powders containing at least one of the elements Cr, Ni or Ce with a binding agent;

b) applying the slip onto the component part to form a slip layer;

c) drying the slip layer at temperatures from room temperature through 300°C;

d) heat treating the slip layer at a temperature range of 750°C to 1200°C in an atmosphere selected from argon and a vacuum to cause a union of the layer with the component part;

e) then alitizing to strengthen the union by diffusion and to compact the [slip] layer to form the adhesion layer, whereby the method is controlled so that the adhesion layer comprises a structure having a grain size less than 75μm and a cavity proportion from 0 through 40%; and

f) applying a heat insulating layer on the adhesive layer.--